



FEATURES

- TO-8 hermetic package
- Optimized die size for maximum signal
- Low capacitance

ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area	9.91mm x 4.28mm		42		mm ²
Responsivity, \mathcal{R}	@ 632nm	0.35	0.40		A/W
Dark Current, I _{dr}	V _R = 10V		11	25	nA
Reverse Breakdown Voltage, V _R	I _R = 10A	25	60		Volts
Capacitance, C	V _R = 10V		85		pF
Rise Time	V _R = 10V		30		nsec
Series Resistance	V _f = 1V		35	100	Ohms

THERMAL PARAMETERS

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	100°C
Lead Soldering Temperature ¹	260°

¹1/16" from case for 10 seconds.

